PC8171xNSZ0F Series

DIP 4pin High CMR, Low Input Current Photocoupler

■ Description
PC8171xNSZ0F Series contains an IRED optically coupled to a phototransistor.
It is packaged in a 4pin DIP, available in SMT gullwing lead-form option.
Input-output isolation voltage (rms) is 5.0kV.
Collector-emitter voltage is 80V, CTR is 100% to 600% at input current of 0.5mA and CMR is MIN. 10kV/µs.

■ Features
1. 4pin DIP package
2. Double transfer mold package (Ideal for Flow Soldering)
3. Low input current type (I<sub>f</sub>=0.5mA)
4. High collector-emitter voltage (V<sub>Ceo</sub> : 80V)
5. High noise immunity due to high common rejection voltage (CMR : MIN. 10kV/µs)
6. High isolation voltage between input and output (V<sub>iso(rms)</sub> : 5.0 kV)
7. Lead-free and RoHS directive compliant

■ Agency approvals/Compliance
1. Recognized by UL1577 (Double protection isolation), file No. E64380 (as model No. PC8171)
2. Package resin : UL flammability grade (94V-0)

■ Applications
1. Programmable controllers
2. Facsimiles
3. Telephones

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■ Internal Connection Diagram

1 Anode
2 Cathode
3 Emitter
4 Collector

■ Outline Dimensions

(Unit : mm)

1. Through-Hole [ex. PC8171xNSZ0F]

- Anode mark
- Rank mark
- Factory identification mark
- Date code
- Epoxy resin

θ : 0 to 13˚

Product mass : approx. 0.23g

2. SMT Gullwing Lead-Form [ex. PC8171xNIP0F]

- Anode mark
- Rank mark
- Factory identification mark
- Date code
- Epoxy resin

Product mass : approx. 0.22g

Plating material : SnCu (Cu : TYP. 2%)
### Date code (2 digit)

<table>
<thead>
<tr>
<th>Year of production</th>
<th>1st digit</th>
<th>2nd digit</th>
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<tbody>
<tr>
<td>A.D.</td>
<td>Mark</td>
<td>A.D.</td>
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<tr>
<td>1990</td>
<td>A</td>
<td>2002</td>
</tr>
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<td>1991</td>
<td>B</td>
<td>2003</td>
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<tr>
<td>1992</td>
<td>C</td>
<td>2004</td>
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<td>1993</td>
<td>D</td>
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<td>1994</td>
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<td>1995</td>
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<td>1997</td>
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<td>1998</td>
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<td>2001</td>
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Repeats in a 20 year cycle

### Factory identification mark

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<tr>
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<th>Country of origin</th>
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<tbody>
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<td>Japan</td>
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<tr>
<td>![mark]</td>
<td>Indonesia</td>
</tr>
<tr>
<td>![mark]</td>
<td>China</td>
</tr>
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</table>

* This factory making is for identification purpose only. Please contact the local SHARP sales representative to see the actual status of the production.

### Rank mark

Refer to the Model Line-up table
### Absolute Maximum Ratings

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Symbol</th>
<th>Rating</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>Input Forward current</td>
<td>$I_F$</td>
<td>10</td>
<td>mA</td>
</tr>
<tr>
<td>$^1$ Peak forward current</td>
<td>$I_{FM}$</td>
<td>200</td>
<td>mA</td>
</tr>
<tr>
<td>Reverse voltage</td>
<td>$V_R$</td>
<td>6</td>
<td>V</td>
</tr>
<tr>
<td>Power dissipation</td>
<td>$P$</td>
<td>15</td>
<td>mW</td>
</tr>
<tr>
<td>Collector-emitter voltage</td>
<td>$V_{CEO}$</td>
<td>80</td>
<td>V</td>
</tr>
<tr>
<td>Emitter-collector voltage</td>
<td>$V_{ECEO}$</td>
<td>6</td>
<td>V</td>
</tr>
<tr>
<td>Collector current</td>
<td>$I_C$</td>
<td>50</td>
<td>mA</td>
</tr>
<tr>
<td>Collector power dissipation</td>
<td>$P_C$</td>
<td>150</td>
<td>mW</td>
</tr>
<tr>
<td>Total power dissipation</td>
<td>$P_{tot}$</td>
<td>170</td>
<td>mW</td>
</tr>
<tr>
<td>$^2$ Isolation voltage</td>
<td>$V_{iso (rms)}$</td>
<td>5.0</td>
<td>kV</td>
</tr>
<tr>
<td>Operating temperature</td>
<td>$T_{opt}$</td>
<td>−30 to +100</td>
<td>°C</td>
</tr>
<tr>
<td>Storage temperature</td>
<td>$T_{stg}$</td>
<td>−55 to +125</td>
<td>°C</td>
</tr>
<tr>
<td>$^2$ Soldering temperature</td>
<td>$T_{sol}$</td>
<td>260</td>
<td>°C</td>
</tr>
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</table>

*1 Pulse width ≤ 100 µs, Duty ratio ≤ 0.001
*2 40 to 60% RH, AC for 1 minute, f=60Hz
*3 For 10s

### Electro-optical Characteristics

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Symbol</th>
<th>Conditions</th>
<th>MIN.</th>
<th>TYP.</th>
<th>MAX.</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>Input Forward voltage</td>
<td>$V_F$</td>
<td>$I_F=10mA$</td>
<td>–</td>
<td>1.2</td>
<td>1.4</td>
<td>V</td>
</tr>
<tr>
<td>Reverse Current</td>
<td>$I_R$</td>
<td>$V_R=4V$</td>
<td>–</td>
<td>–</td>
<td>10</td>
<td>µA</td>
</tr>
<tr>
<td>Terminal capacitance</td>
<td>$C_t$</td>
<td>$V=0$, f=1kHz</td>
<td>–</td>
<td>30</td>
<td>250</td>
<td>pF</td>
</tr>
<tr>
<td>Collector dark current</td>
<td>$I_{CEO}$</td>
<td>$V_{CE}=50V$, $I_F=0$</td>
<td>–</td>
<td>–</td>
<td>100</td>
<td>nA</td>
</tr>
<tr>
<td>Collector-emitter breakdown voltage</td>
<td>$BV_{CEO}$</td>
<td>$I_F=0.1mA$, $I_F=0$</td>
<td>80</td>
<td>–</td>
<td>–</td>
<td>V</td>
</tr>
<tr>
<td>Emitter-collector breakdown voltage</td>
<td>$BV_{ECEO}$</td>
<td>$I_F=10µA$, $I_F=0$</td>
<td>6</td>
<td>–</td>
<td>–</td>
<td>V</td>
</tr>
<tr>
<td>Collector current</td>
<td>$I_C$</td>
<td>$I_F=0.5mA$, $V_{CE}=5V$</td>
<td>0.5</td>
<td>–</td>
<td>3.0</td>
<td>mA</td>
</tr>
<tr>
<td>Collector-emitter saturation voltage</td>
<td>$V_{CE (sat)}$</td>
<td>$I_F=10mA$, $I_F=1mA$</td>
<td>–</td>
<td>–</td>
<td>0.2</td>
<td>V</td>
</tr>
<tr>
<td>Isolation resistance</td>
<td>$R_{ISO}$</td>
<td>DC500V, 40 to 60% RH</td>
<td>$5\times10^{10}$</td>
<td>$1\times10^{11}$</td>
<td>–</td>
<td>Ω</td>
</tr>
<tr>
<td>Floating capacitance</td>
<td>$C_f$</td>
<td>$V=0$, f=1MHz</td>
<td>–</td>
<td>0.6</td>
<td>1.0</td>
<td>pF</td>
</tr>
<tr>
<td>Response time Rise time</td>
<td>$t_r$</td>
<td>$V_{CE}=2V$, $I_C=2mA$, $R_L=100Ω$</td>
<td>–</td>
<td>4</td>
<td>18</td>
<td>µs</td>
</tr>
<tr>
<td>Response time Fall time</td>
<td>$t_f$</td>
<td>$V_{CE}=2V$, $I_C=2mA$, $R_L=100Ω$</td>
<td>–</td>
<td>3</td>
<td>18</td>
<td>µs</td>
</tr>
<tr>
<td>Common mode rejection voltage</td>
<td>CMR</td>
<td>$T_s=25°C$, $R_L=470Ω$, $V_{CM}=1.5kV$ (peak)</td>
<td>10</td>
<td>–</td>
<td>–</td>
<td>kV/µs</td>
</tr>
</tbody>
</table>

Sheet No.: D2-A03302EN
## Model Line-up

<table>
<thead>
<tr>
<th>Model No.</th>
<th>Package</th>
<th>Through-Hole</th>
<th>SMT Gullwing</th>
<th>Rank mark</th>
<th>IC [mA] (I_F=0.5mA, V_CE=5V, T_a=25°C)</th>
</tr>
</thead>
<tbody>
<tr>
<td>PC81710NSZ0F</td>
<td>PC81710NIP0F</td>
<td>with or without</td>
<td>0.5 to 3.0</td>
<td></td>
<td></td>
</tr>
<tr>
<td>PC81711NSZ0F</td>
<td>PC81711NIP0F</td>
<td>A</td>
<td>0.6 to 1.5</td>
<td></td>
<td></td>
</tr>
<tr>
<td>PC81712NSZ0F</td>
<td>PC81712NIP0F</td>
<td>B</td>
<td>0.8 to 2.0</td>
<td></td>
<td></td>
</tr>
<tr>
<td>PC81713NSZ0F</td>
<td>PC81713NIP0F</td>
<td>C</td>
<td>1.0 to 2.5</td>
<td></td>
<td></td>
</tr>
<tr>
<td>PC81715NSZ0F</td>
<td>PC81715NIP0F</td>
<td>A or B</td>
<td>0.6 to 2.0</td>
<td></td>
<td></td>
</tr>
<tr>
<td>PC81716NSZ0F</td>
<td>PC81716NIP0F</td>
<td>B or C</td>
<td>0.8 to 2.5</td>
<td></td>
<td></td>
</tr>
<tr>
<td>PC81718NSZ0F</td>
<td>PC81718NIP0F</td>
<td>A, B or C</td>
<td>0.6 to 2.5</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

Please contact a local SHARP sales representative to inquire about production status.
Fig. 1 Test Circuit for Common Mode Rejection Voltage

1) \( V_{cp} \): Voltage which is generated by displacement current in floating capacitance between primary and secondary side.

RL = 470 Ω

VCC = 9V

Fig. 2 Forward Current vs. Ambient Temperature

Fig. 3 Diode Power Dissipation vs. Ambient Temperature

Fig. 4 Collector Power Dissipation vs. Ambient Temperature

Fig. 5 Total Power Dissipation vs. Ambient Temperature
Fig. 6 Peak Forward Current vs. Duty Ratio

Fig. 7 Forward Current vs. Forward Voltage

Fig. 8 Current Transfer Ratio vs. Forward Current

Fig. 9 Collector Current vs. Collector-emitter Voltage

Fig. 10 Relative Current Transfer Ratio vs. Ambient Temperature

Fig. 11 Collector - emitter Saturation Voltage vs. Ambient Temperature
Fig.12 Collector Dark Current vs. Ambient Temperature

Fig.13 Response Time vs. Load Resistance (active region)

Fig.14 Response Time vs. Load Resistance (saturation region)

Fig.15 Test Circuit for Response Time

Fig.16 Frequency Response

Fig.17 Collector-emitter Saturation Voltage vs. Forward Current

Remarks: Please be aware that all data in the graph are just for reference and not for guarantee.
Design Considerations

- **Design guide**
  
  While operating at $I_F<0.5\text{mA}$, CTR variation may increase.
  Please make design considering this fact.

  In case that some sudden big noise caused by voltage variation is provided between primary and secondary terminals of photocoupler some current caused by it is floating capacitance may be generated and result in false operation since current may go through IRED or current may change.
  If the photocoupler may be used under the circumstances where noise will be generated we recommend to use the bypass capacitors at the both ends of IRED.

  This product is not designed against irradiation and incorporates non-coherent IRED.

- **Degradation**
  
  In general, the emission of the IRED used in photocouplers will degrade over time.
  In the case of long term operation, please take the general IRED degradation (50% degradation over 5 years) into the design consideration.

- **Recommended Foot Print (reference)**

  ![](image)

  (Unit : mm)

  ✤ For additional design assistance, please review our corresponding Optoelectronic Application Notes.
Manufacturing Guidelines

Soldering Method

Reflow Soldering:
Reflow soldering should follow the temperature profile shown below.
Soldering should not exceed the curve of temperature profile and time.
Please don't solder more than twice.

Flow Soldering:
Due to SHARP's double transfer mold construction submersion in flow solder bath is allowed under the below listed guidelines.

Flow soldering should be completed below 270°C and within 10s.
Preheating is within the bounds of 100 to 150°C and 30 to 80s.
Please don't solder more than twice.

Hand soldering
Hand soldering should be completed within 3s when the point of solder iron is below 400°C.
Please don't solder more than twice.

Other notices
Please test the soldering method in actual condition and make sure the soldering works fine, since the impact on the junction between the device and PCB varies depending on the tooling and soldering conditions.
● **Cleaning instructions**

**Solvent cleaning:**
Solvent temperature should be 45˚C or below Immersion time should be 3 minutes or less

**Ultrasonic cleaning:**
The impact on the device varies depending on the size of the cleaning bath, ultrasonic output, cleaning time, size of PCB and mounting method of the device. Therefore, please make sure the device withstands the ultrasonic cleaning in actual conditions in advance of mass production.

**Recommended solvent materials:**
Ethyl alcohol, Methyl alcohol and Isopropyl alcohol
In case the other type of solvent materials are intended to be used, please make sure they work fine in actual using conditions since some materials may erode the packaging resin.

● **Presence of ODC**
This product shall not contain the following materials.
And they are not used in the production process for this product.
Regulation substances: CFCs, Halon, Carbon tetrachloride, 1,1,1-Trichloroethane (Methylchloroform)

Specific brominated flame retardants such as the PBBOs and PBBs are not used in this product at all.

This product shall not contain the following materials banned in the RoHS Directive (2002/95/EC).
- Lead, Mercury, Cadmium, Hexavalent chromium, Polybrominated biphenyls (PBB), Polybrominated diphenyl ethers (PBDE).
Package specification

Sleeve package

Package materials
- Sleeve: HIPS (with anti-static material)
- Stopper: Styrene-Elastomer

Package method
- MAX. 100pcs of products shall be packaged in a sleeve.
- Both ends shall be closed by tabbed and tableless stoppers.
- The product shall be arranged in the sleeve with its anode mark on the tableless stopper side.
- MAX. 20 sleeves in one case.

Sleeve outline dimensions

(Unit: mm)
● Tape and Reel package
Package materials
  Carrier tape : PS
  Cover tape : PET (three layer system)
  Reel : PS

Carrier tape structure and Dimensions

Dimensions List (Unit : mm)

<table>
<thead>
<tr>
<th>A</th>
<th>B ±t</th>
<th>C ±t</th>
<th>D ±t</th>
<th>E ±t</th>
<th>F ±t</th>
<th>G ±t</th>
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<tbody>
<tr>
<td>16</td>
<td>±0.3</td>
<td>7.5</td>
<td>±0.1</td>
<td>1.75</td>
<td>±0.1</td>
<td>8.0</td>
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<td>I</td>
<td>J</td>
<td>K</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>10</td>
<td>±0.1</td>
<td>0.4±0.05</td>
<td>4.2±0.1</td>
<td>5.1±0.1</td>
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Reel structure and Dimensions

Dimensions List (Unit : mm)

<table>
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<tr>
<th>a</th>
<th>b ±t</th>
<th>c ±t</th>
<th>d ±t</th>
</tr>
</thead>
<tbody>
<tr>
<td>330</td>
<td>17.5±1.5</td>
<td>100±1.0</td>
<td>13±0.5</td>
</tr>
<tr>
<td>e</td>
<td>f</td>
<td>g</td>
<td></td>
</tr>
<tr>
<td>23±1.0</td>
<td>2.0±0.5</td>
<td>2.0±0.5</td>
<td></td>
</tr>
</tbody>
</table>

Direction of product insertion

[Pull-out direction]

[Packing : 2 000pcs/reel]
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    --- Office automation equipment
    --- Test and measurement equipment
    --- Industrial control
    --- Audio visual equipment
    --- Consumer electronics
  (ii) Measures such as fail-safe function and redundant design should be taken to ensure reliability and safety when SHARP devices are used for or in connection with equipment that requires higher reliability such as:
    --- Transportation control and safety equipment (i.e., aircraft, trains, automobiles, etc.)
    --- Traffic signals
    --- Gas leakage sensor breakers
    --- Alarm equipment
    --- Various safety devices, etc.

(iii) SHARP devices shall not be used for or in connection with equipment that requires an extremely high level of reliability and safety such as:
    --- Space applications
    --- Telecommunication equipment [trunk lines]
    --- Nuclear power control equipment
    --- Medical and other life support equipment (e.g., scuba).

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